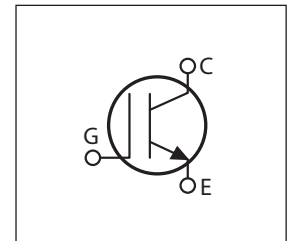
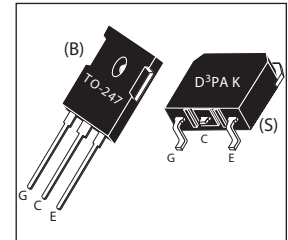


## Thunderbolt IGBT®

The Thunderbolt IGBT® is a new generation of high voltage power IGBTs. Using Non-Punch Through Technology, the Thunderbolt IGBT® offers superior ruggedness and ultrafast switching speed.

- Low Forward Voltage Drop
- High Freq. Switching to 100KHz
- Low Tail Current
- Ultra Low Leakage Current
- RBSOA and SCSOA Rated




### MAXIMUM RATINGS

All Ratings:  $T_C = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	APT50GT60BR_SR(G)	UNIT
$V_{CES}$	Collector-Emitter Voltage	600	Volts
$V_{GE}$	Gate-Emitter Voltage	$\pm 30$	
$I_{C1}$	Continuous Collector Current <sup>7</sup> @ $T_C = 25^\circ\text{C}$	110	Amps
$I_{C2}$	Continuous Collector Current @ $T_C = 110^\circ\text{C}$	52	
$I_{CM}$	Pulsed Collector Current <sup>1</sup>	150	
SSOA	Switching Safe Operating Area @ $T_j = 150^\circ\text{C}$	150A @ 600V	
$P_D$	Total Power Dissipation	446	Watts
$T_j, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to 150	°C
$T_L$	Max. Lead Temp. for Soldering: 0.063" from Case for 10 Sec.	300	

### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	Units
$V_{(BR)CES}$	Collector-Emitter Breakdown Voltage ( $V_{GE} = 0V, I_C = 2mA$ )	600			Volts
$V_{GE(TH)}$	Gate Threshold Voltage ( $V_{CE} = V_{GE}, I_C = 1mA, T_j = 25^\circ\text{C}$ )	3	4	5	
$V_{CE(ON)}$	Collector-Emitter On Voltage ( $V_{GE} = 15V, I_C = 50A, T_j = 25^\circ\text{C}$ )	1.7	2.0	2.5	
	Collector-Emitter On Voltage ( $V_{GE} = 15V, I_C = 50A, T_j = 125^\circ\text{C}$ )		2.2		
$I_{CES}$	Collector Cut-off Current ( $V_{CE} = 600V, V_{GE} = 0V, T_j = 25^\circ\text{C}$ ) <sup>2</sup>			25	μA
	Collector Cut-off Current ( $V_{CE} = 600V, V_{GE} = 0V, T_j = 125^\circ\text{C}$ ) <sup>2</sup>			TBD	
$I_{GES}$	Gate-Emitter Leakage Current ( $V_{GE} = \pm 20V$ )			120	nA

 **CAUTION:** These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

DYNAMIC CHARACTERISTICS

APT50GT60BR\_SR(G)

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT	
$C_{ies}$	Input Capacitance	Capacitance $V_{GE} = 0V, V_{CE} = 25V$ $f = 1 \text{ MHz}$		2660		pF	
$C_{oes}$	Output Capacitance			250			
$C_{res}$	Reverse Transfer Capacitance			153			
$V_{GEP}$	Gate-to-Emitter Plateau Voltage	Gate Charge $V_{GE} = 15V$ $V_{CE} = 300V$ $I_C = 50A$		7.5		V	
$Q_g$	Total Gate Charge <sup>3</sup>			240		nC	
$Q_{ge}$	Gate-Emitter Charge			20			
$Q_{gc}$	Gate-Collector ("Miller") Charge			110			
SSOA	Switching Safe Operating Area	$T_J = 150^\circ\text{C}, R_G = 4.3\Omega, V_{GE} = 15V, L = 100\mu\text{H}, V_{CE} = 600V$	150			A	
$t_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C) $V_{CC} = 400V$ $V_{GE} = 15V$ $I_C = 50A$ $R_G = 4.3\Omega$ $T_J = +25^\circ\text{C}$		14		ns	
$t_r$	Current Rise Time			32			
$t_{d(off)}$	Turn-off Delay Time			240			
$t_f$	Current Fall Time			36			
$E_{on1}$	Turn-on Switching Energy <sup>4</sup>				995		$\mu\text{J}$
$E_{on2}$	Turn-on Switching Energy (Diode) <sup>5</sup>				1110		
$E_{off}$	Turn-off Switching Energy <sup>6</sup>				1070		
$t_{d(on)}$	Turn-on Delay Time	Inductive Switching (125°C) $V_{CC} = 400V$ $V_{GE} = 15V$ $I_C = 50A$ $R_G = 4.3\Omega$ $T_J = +125^\circ\text{C}$		14		ns	
$t_r$	Current Rise Time			32			
$t_{d(off)}$	Turn-off Delay Time			270			
$t_f$	Current Fall Time			95			
$E_{on1}$	Turn-on Switching Energy <sup>4</sup>				1035		$\mu\text{J}$
$E_{on2}$	Turn-on Switching Energy (Diode) <sup>5</sup>				1655		
$E_{off}$	Turn-off Switching Energy <sup>6</sup>				1505		

THERMAL AND MECHANICAL CHARACTERISTICS

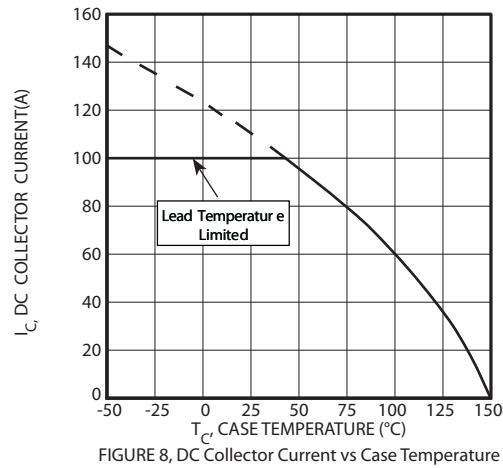
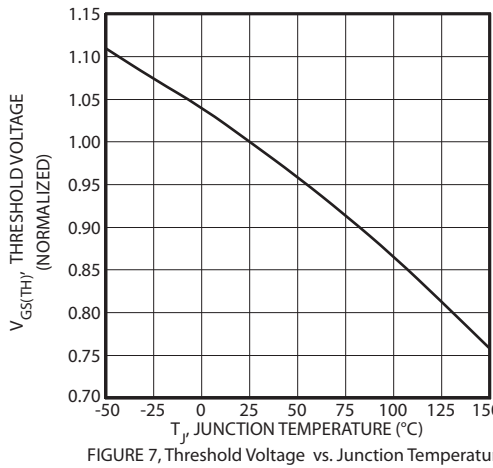
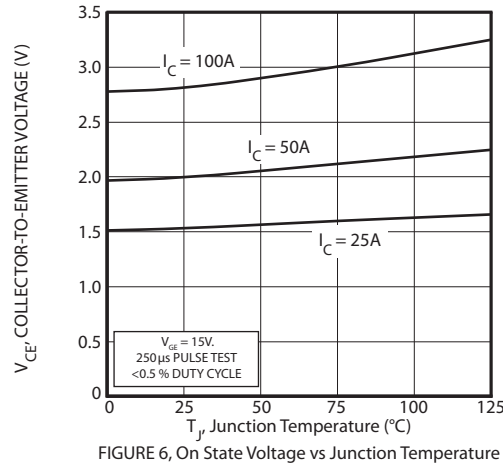
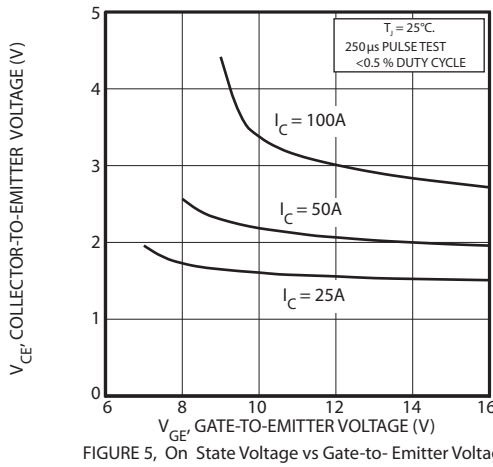
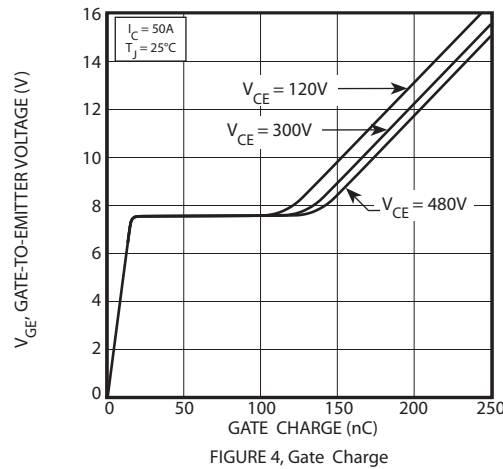
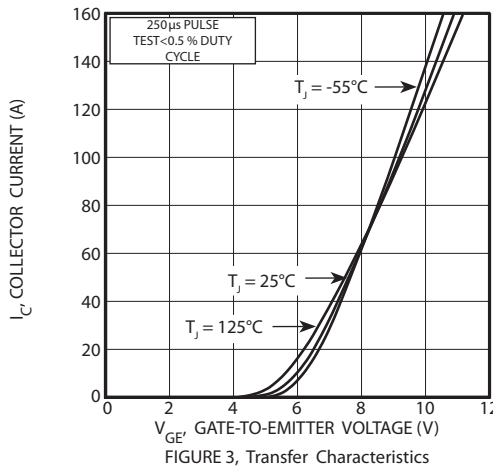
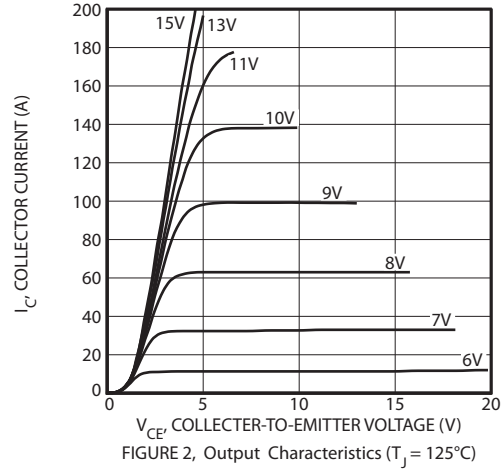
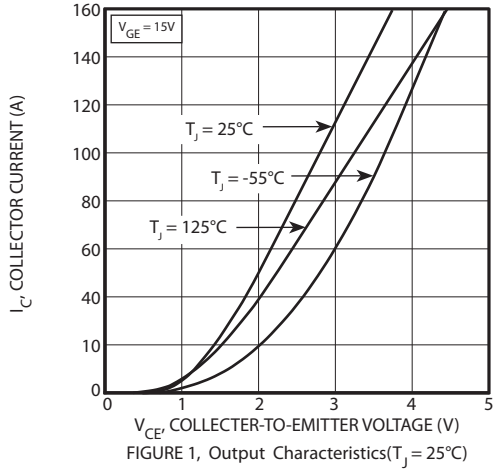
Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case (IGBT)			.28	$^\circ\text{C/W}$
$R_{\theta JC}$	Junction to Case (DIODE)			N/A	
$W_T$	Package Weight		5.9		gm

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② For Combi devices,  $I_{ces}$  includes both IGBT and FRED leakages
- ③ See MIL-STD-750 Method 3471.
- ④  $E_{on1}$  is the clamped inductive turn-on energy of the IGBT only, without the effect of a commutating diode reverse recovery current adding to the IGBT turn-on loss. Tested in inductive switching test circuit shown in figure 21, but with a Silicon Carbide diode.
- ⑤  $E_{on2}$  is the clamped inductive turn-on energy that includes a commutating diode reverse recovery current in the IGBT turn-on switching loss. (See Figures 21, 22.)
- ⑥  $E_{off}$  is the clamped inductive turn-off energy measured in accordance with JEDEC standard JESD24-1. (See Figures 21, 23.)
- ⑦ Continuous current limited by package lead temperature.

Microsemi reserves the right to change, without notice, the specifications and information contained herein.

TYPICAL PERFORMANCE CURVES

APT50GT60BR\_SR(G)



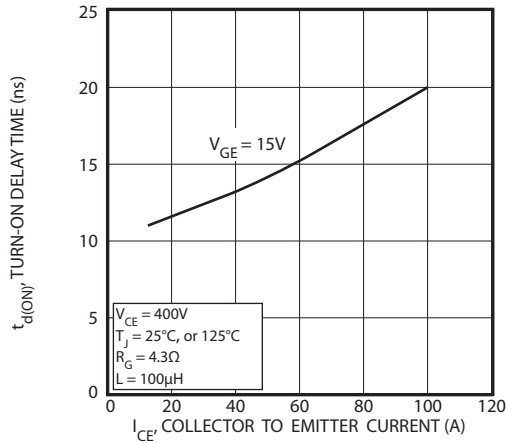


FIGURE 9, Turn-On Delay Time vs Collector Current

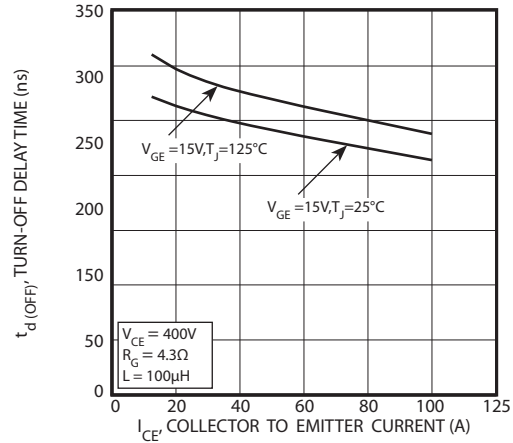


FIGURE 10, Turn-Off Delay Time vs Collector Current

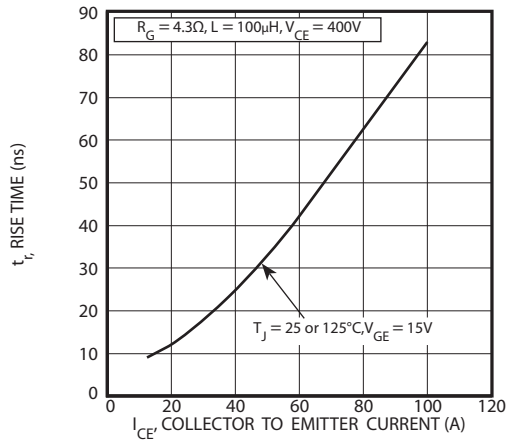


FIGURE 11, Current Rise Time vs Collector Current

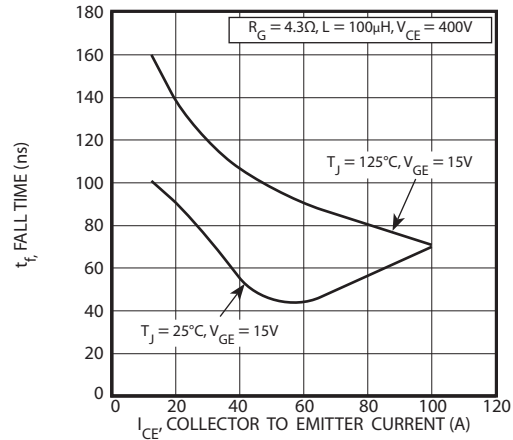


FIGURE 12, Current Fall Time vs Collector Current

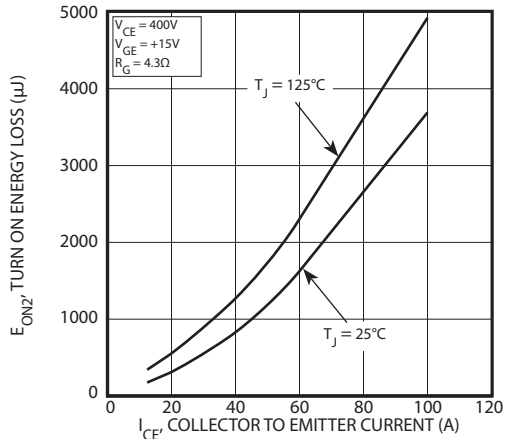


FIGURE 13, Turn-On Energy Loss vs Collector Current

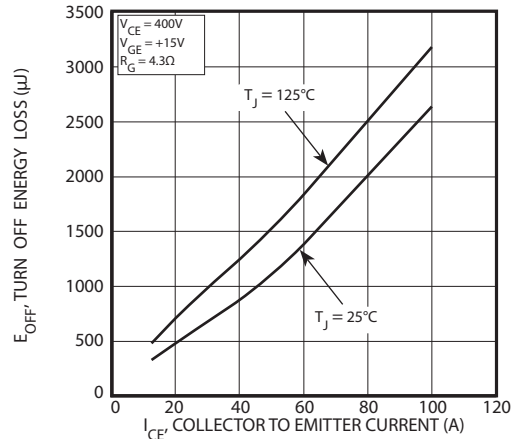


FIGURE 14, Turn Off Energy Loss vs Collector Current

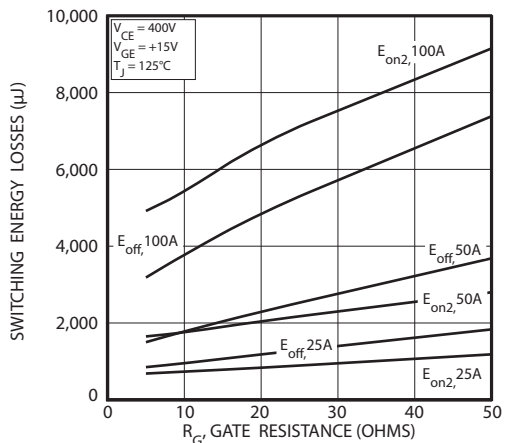


FIGURE 15, Switching Energy Losses vs. Gate Resistance

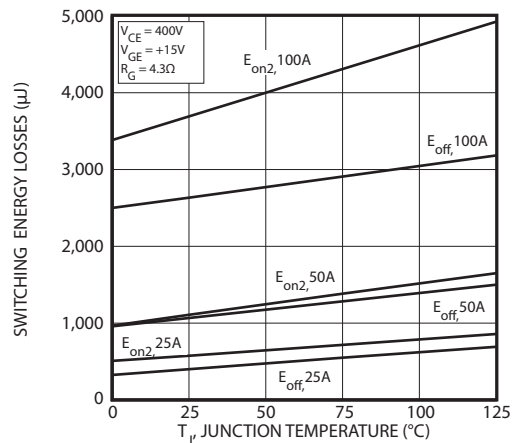


FIGURE 16, Switching Energy Losses vs Junction Temperature

TYPICAL PERFORMANCE CURVES

APT50GT60BR\_SR(G)

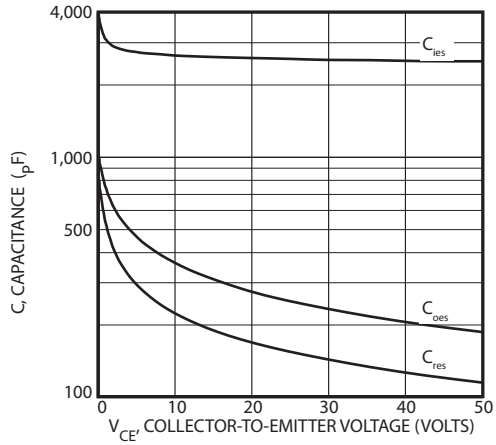


Figure 17, Capacitance vs Collector-To-Emitter Voltage

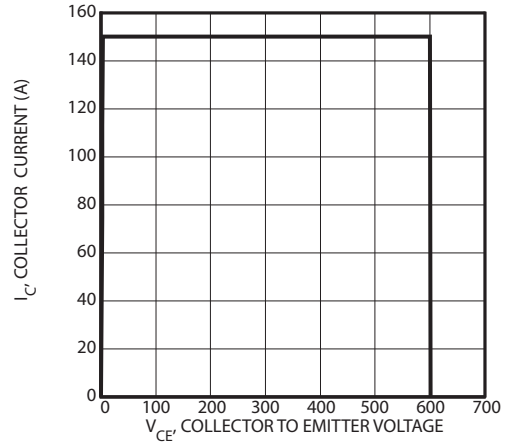


Figure 18, Minimum Switching Safe Operating Area

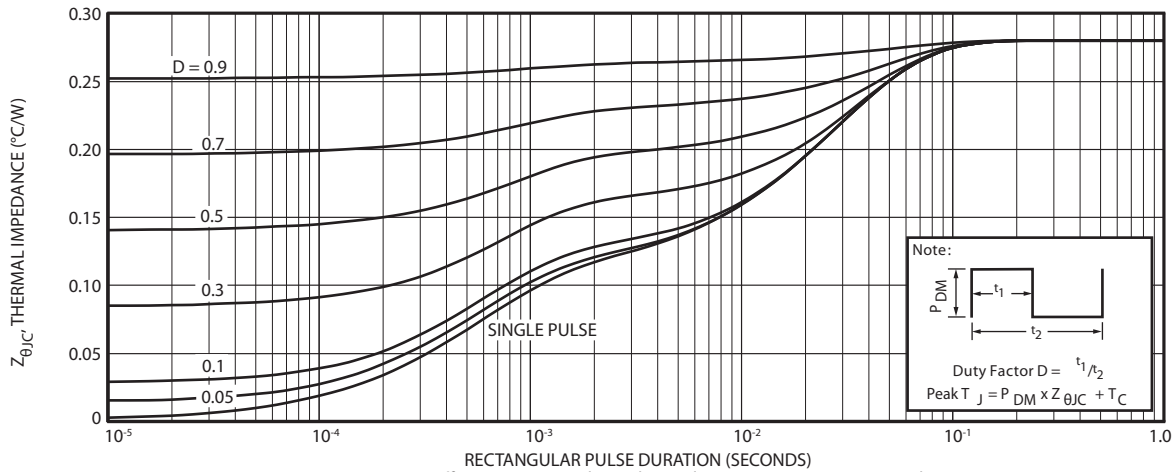


Figure 19a, Maximum Effective Transient Thermal Impedance, Junction-To-Case vs Pulse Duration

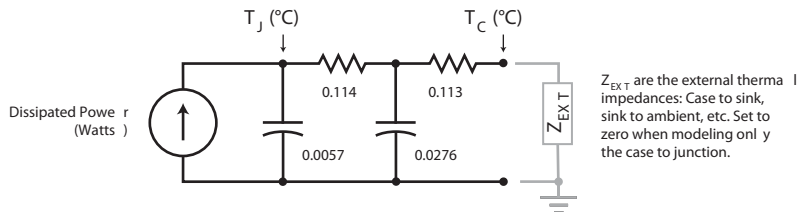


FIGURE 19b, TRANSIENT THERMAL IMPEDANCE MODEL

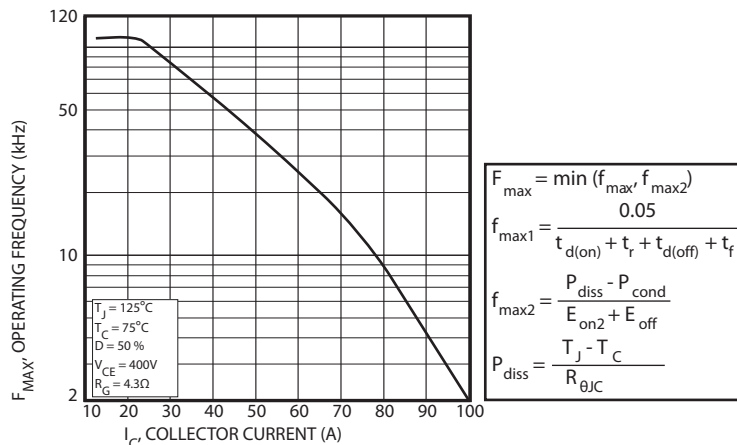


Figure 20, Operating Frequency vs Collector Current

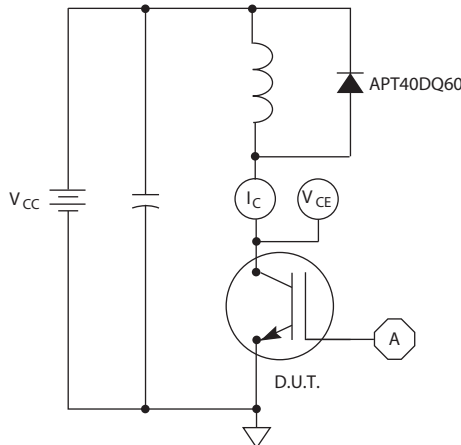


Figure 21, Inductive Switching Test Circuit

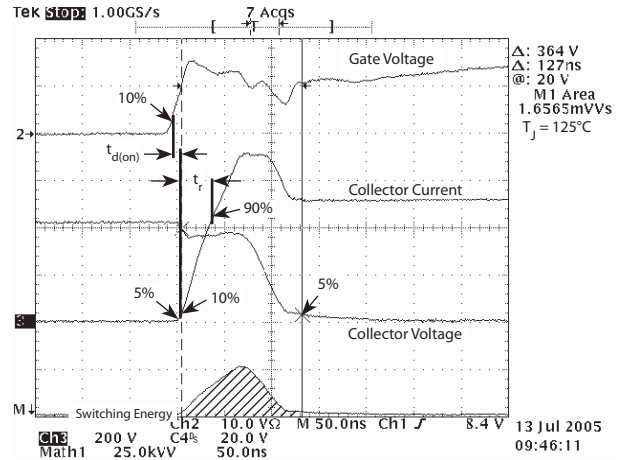


Figure 22, Turn-on Switching Waveforms and Definitions

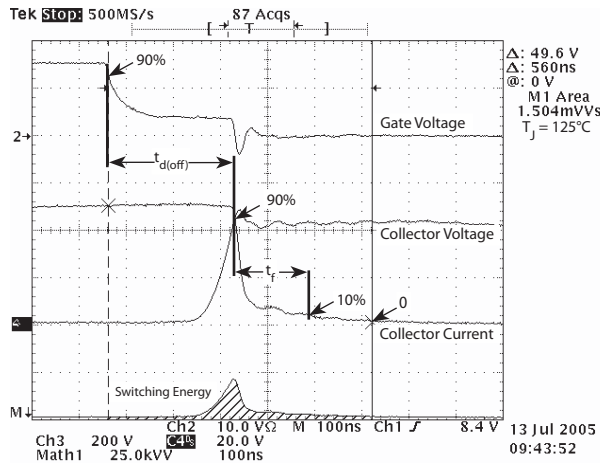
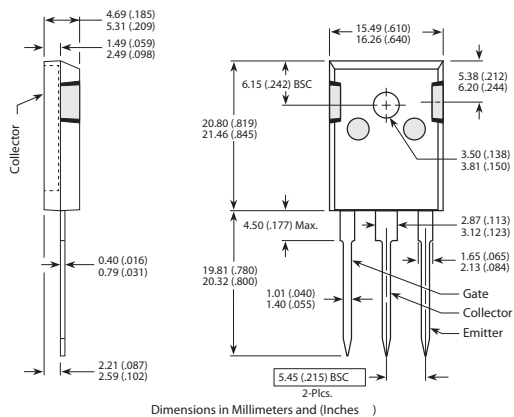


Figure 23, Turn-off Switching Waveforms and Definitions

TO-247 Package Outline

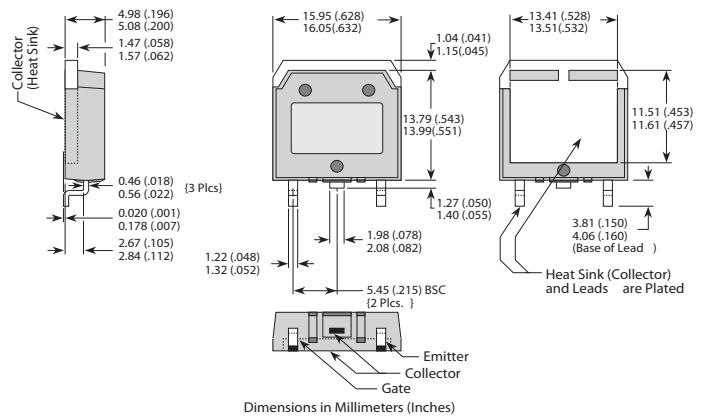
(e1) SAC: Tin, Silver, Copper



Dimensions in Millimeters and (Inches)

D<sup>3</sup>PAK Package Outline

(e3) SAC: Tin, Silver, Copper



Dimensions in Millimeters (Inches)

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: [org@lifeelectronics.ru](mailto:org@lifeelectronics.ru)